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RELEASE HISTORY

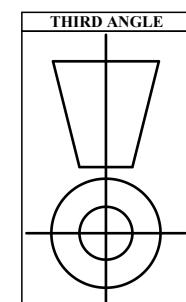
REVISION	DESCRIPTION	DATE
v1.0	Initial Prototype	09/04/2021
v2.0	Second Prototype	07/06/2021
v3.0	Design Candidate	05/08/2021
v4.3	Final Design	10/12/2021

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Board Fabrication Statistics

Item	Value
Board Height	144.50mm
Board Width	207.50mm
Board Area	29983.75sq.mm
Net Count	0
Pad Count	12
Hole Count	12
Via Count	0
Slot Hole Count	0



APPROVALS	DATE	UNIVERSITY OF CAPE TOWN	CONTACT:	ALTERNATIVE:
ENGINEER: LD STANTON	10/12/2021	DEPARTMENT OF ELECTRICAL ENGINEERING	LAWRENCE STANTON	JUSTIN PEAD
CHECKER: JC Pead	--/-/-	CAPE TOWN	STNLAW003@myuct.ac.za	justin.pead@uct.ac.za
REFERENCE DOCUMENTS		SOUTH AFRICA	7701	
BOM DOC: Bill of Materials.csv		TITLE: SIO2MKR		
CPL DOC: Pick and Place.csv			USB Split Rail Power Supply for Breadboards	
ASM DOC: Assembly.PCDBdwf		VARIANT: [No Variations]	REVISION	v4.3 2021/12/10
SCH DOC: Main.SchDoc		SIZE: A4	DWG:	
PCB DOC: Panel.PcbDoc		SCALE: 1:1	FILE: Panel Fabrication.PCBDwf	SHEET 1 OF 11
FABRICATION				

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Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.03mm	SM-001	Solder Mask	GTS
PbSn	Top Surface Finish	0.02mm		Surface Finish	
CF-004	Top Layer	0.04mm		Signal	GTL
	<i>Core</i>	<i>1.44mm</i>	<i>Core-043</i>	<i>Dielectric</i>	
CF-004	Bottom Layer	0.04mm		Signal	GBL
PbSn	Bottom Surface Finish	0.02mm		Surface Finish	
Surface Material	Bottom Solder	0.03mm	SM-001	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
Total thickness: 1.60mm					

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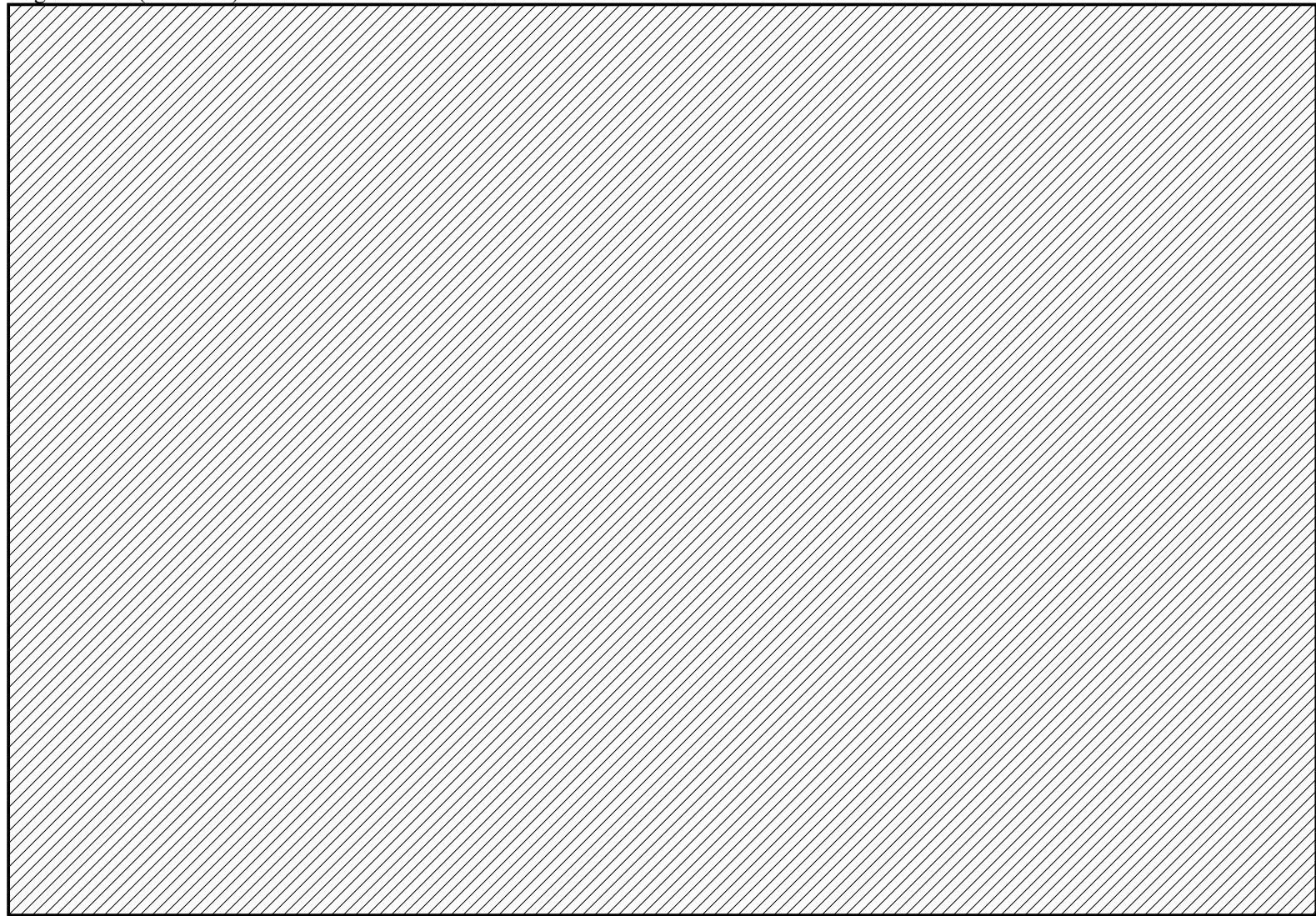
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Region View (Scale 1:1)

SIZE:
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FABRICATION

SCALE: 1:1

FILE: Panel Fabrication.PCBDwF

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Drill Table

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via / Pad	Pad Shape	Hole Tolerance	Hole Length
+	392	0.50mm(20mil)	Plated	Round	Top Layer - Bottom Layer	Via		+0.13mm(5mil)/-0.08mm(3mil)	
◇	32	0.60mm(24mil)	Plated	Slot	Top Layer - Bottom Layer	Pad	Rounded		
B	16	0.70mm(28mil)	Non-Plated	Round	Top Layer - Bottom Layer	Pad	Rounded		
□	80	0.79mm(31mil)	Non-Plated	Round	Top Layer - Bottom Layer	Pad	Rounded		
☒	24	0.80mm(31mil)	Plated	Round	Top Layer - Bottom Layer	Pad	(Mixed)		
回	64	0.80mm(31mil)	Plated	Round	Top Layer - Bottom Layer	(Mixed)	(Mixed)	+0.13mm(5mil)/-0.08mm(3mil)	
☒	160	0.90mm(35mil)	Plated	Round	Top Layer - Bottom Layer	Pad	Rounded	+0.13mm(5mil)/-0.08mm(3mil)	
☒	176	0.90mm(35mil)	Plated	(Mixed)	Top Layer - Bottom Layer	Pad	Rounded		
A	24	0.91mm(36mil)	Plated	Round	Top Layer - Bottom Layer	Pad	Rounded		
▽	48	1.10mm(43mil)	Plated	Round	Top Layer - Bottom Layer	Pad	Rounded	+0.13mm(5mil)/-0.08mm(3mil)	
☒	40	1.15mm(45mil)	Non-Plated	Round	Top Layer - Bottom Layer	Pad	Rounded	+0.13mm(5mil)/-0.08mm(3mil)	
☒	12	1.15mm(45mil)	Non-Plated	Round	Top Layer - Bottom Layer	Pad	Rounded		
☒	40	1.20mm(47mil)	Plated	Round	Top Layer - Bottom Layer	Pad	Rounded	+0.13mm(5mil)/-0.08mm(3mil)	
○	32	1.80mm(71mil)	Plated	Slot	Top Layer - Bottom Layer	Pad	Rounded	+0.13mm(5mil)/-0.08mm(3mil)	
	1140 Total								

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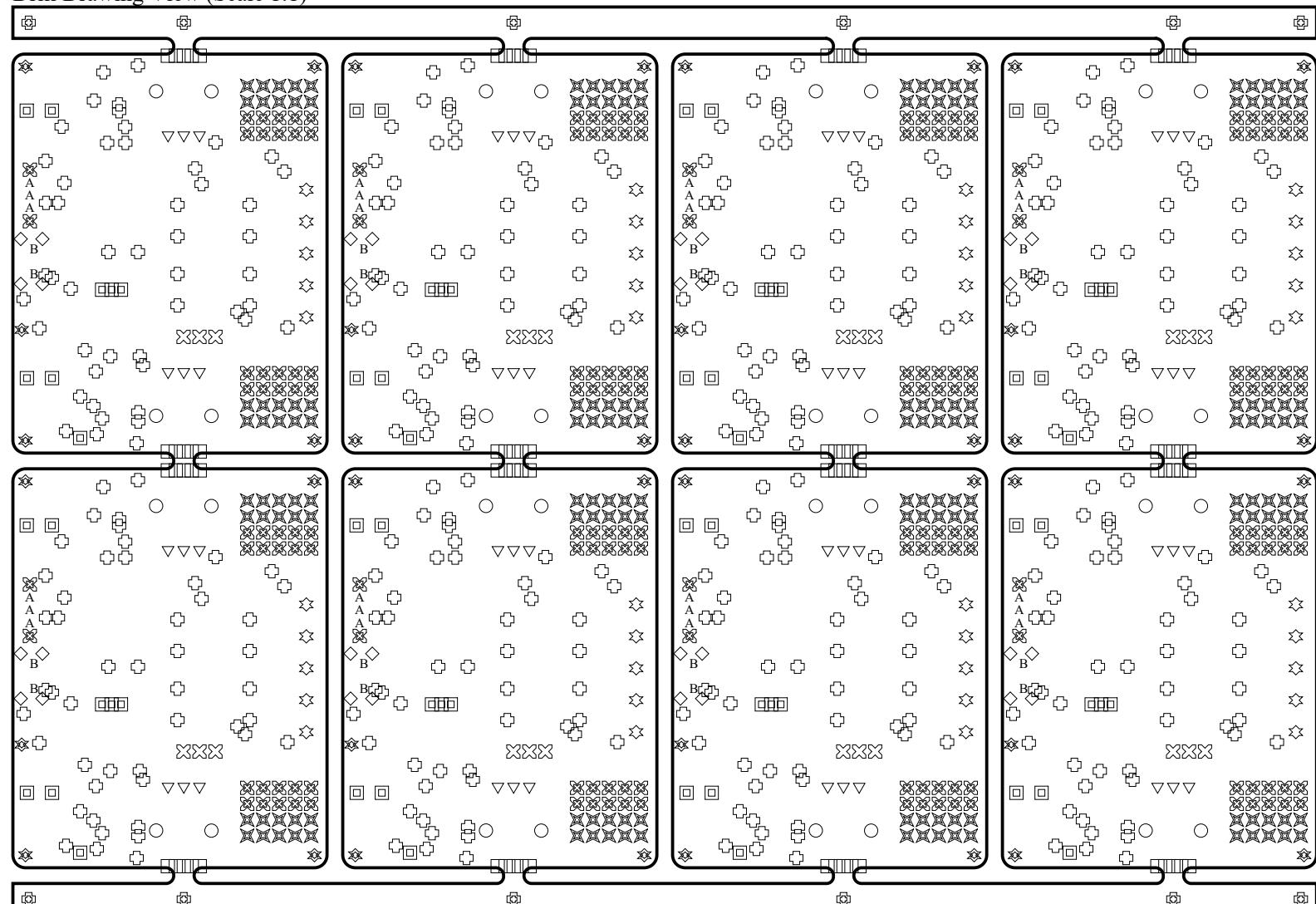
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Drill Drawing View (Scale 1:1)

SIZE:
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FABRICATION

SCALE: 1:1 FILE: Panel Fabrication.PCBBdwf SHEET 5 OF 11

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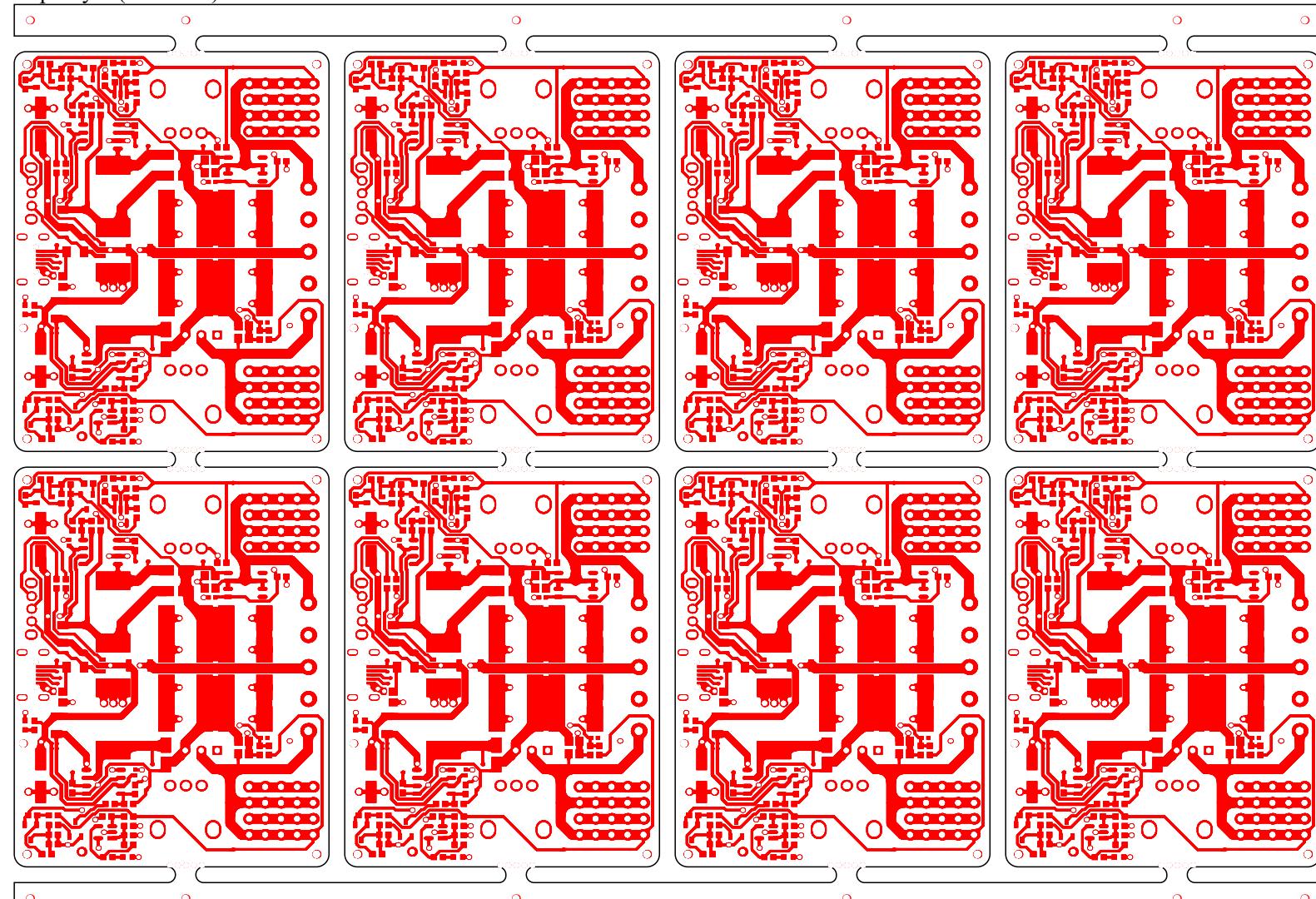
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Top Layer (Scale 1:1)

SIZE:
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DWG:

FABRICATION

SCALE: 1:1

FILE: Panel Fabrication.PCBBdwf

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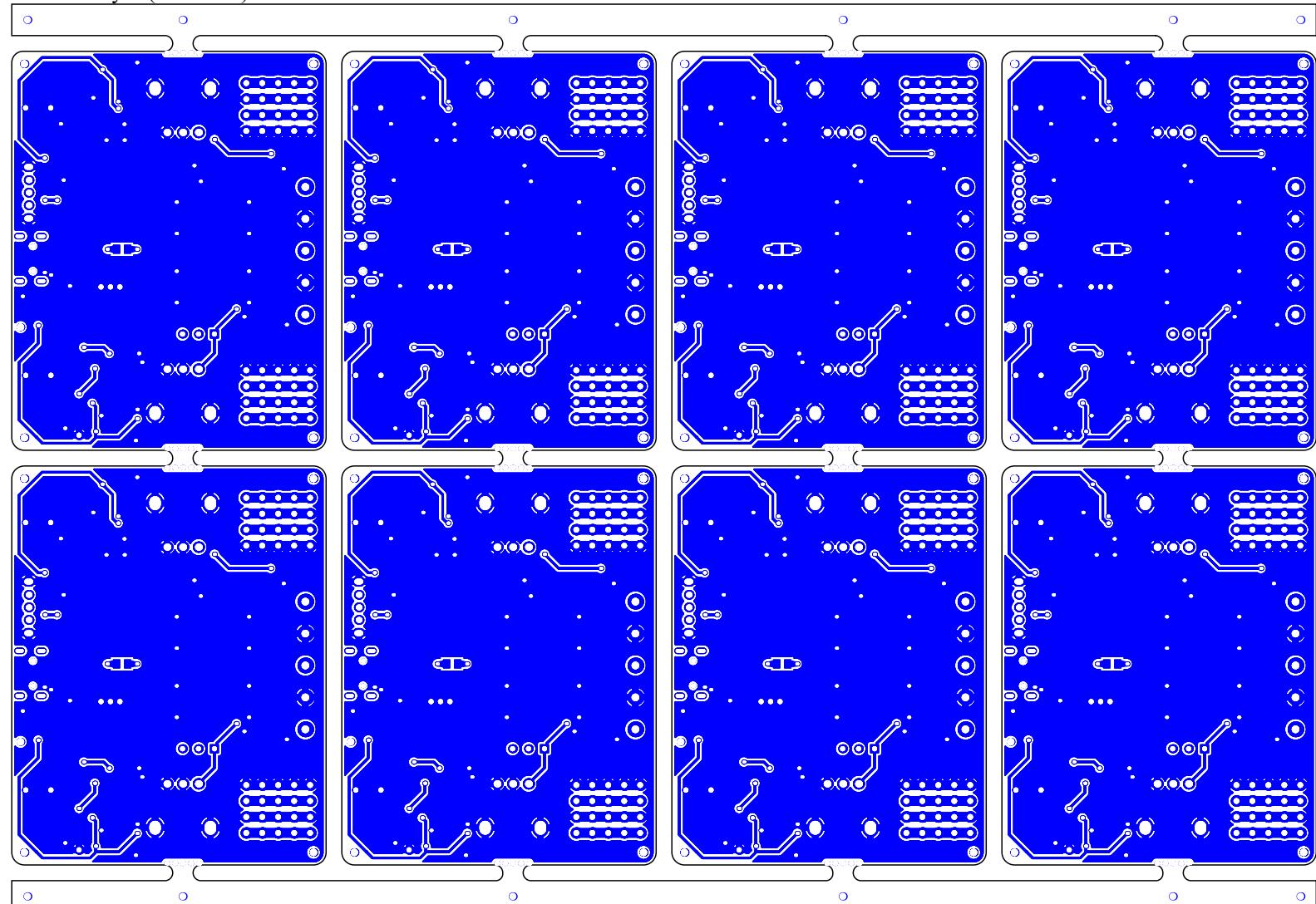
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Bottom Layer (Scale 1:1)

SIZE:
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DWG:

FABRICATION

SCALE: 1:1

FILE: Panel Fabrication.PCBDwF

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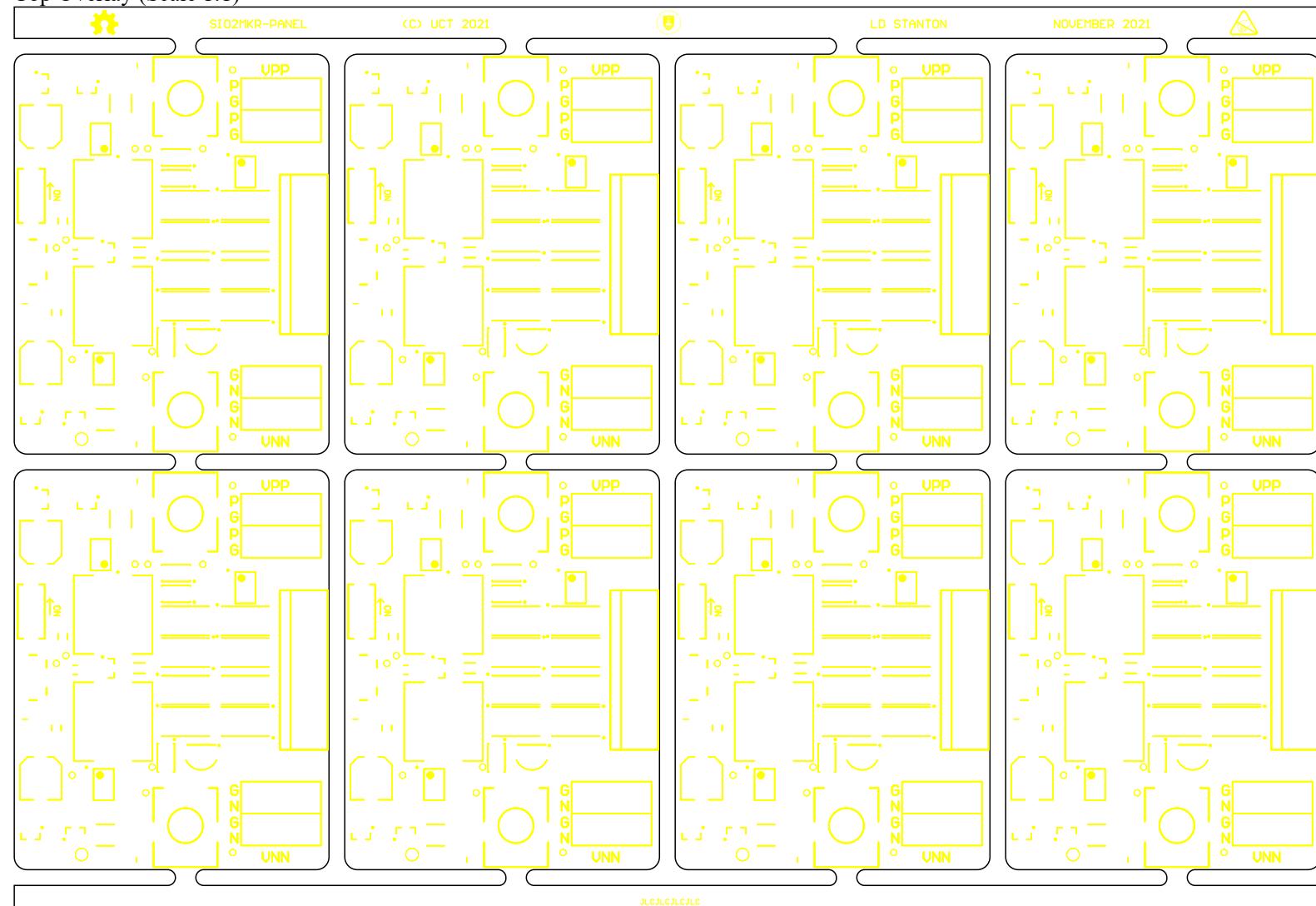
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Top Overlay (Scale 1:1)

SIZE:
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DWG:

FABRICATION

SCALE: 1:1

FILE: Panel Fabrication.PCBBdwf

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Bottom Overlay (Scale 1:1)

SIZE: A4 DWG:

SCALE: 1:1 **FILE:** Panel Fabrication.PCBDwf

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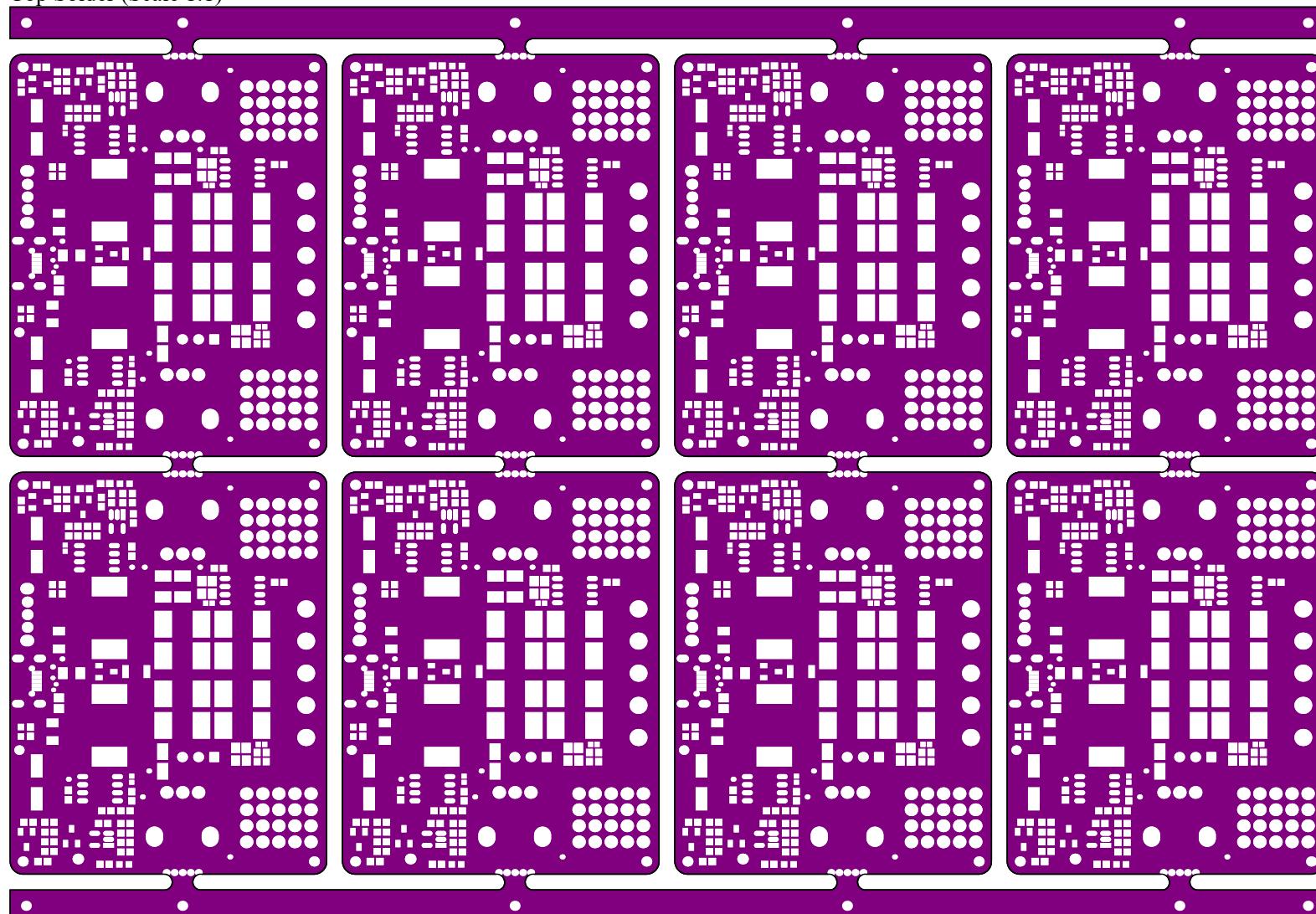
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Top Solder (Scale 1:1)

SIZE:
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DWG:

FABRICATION

SCALE: 1:1

FILE: Panel Fabrication.PCBDwf

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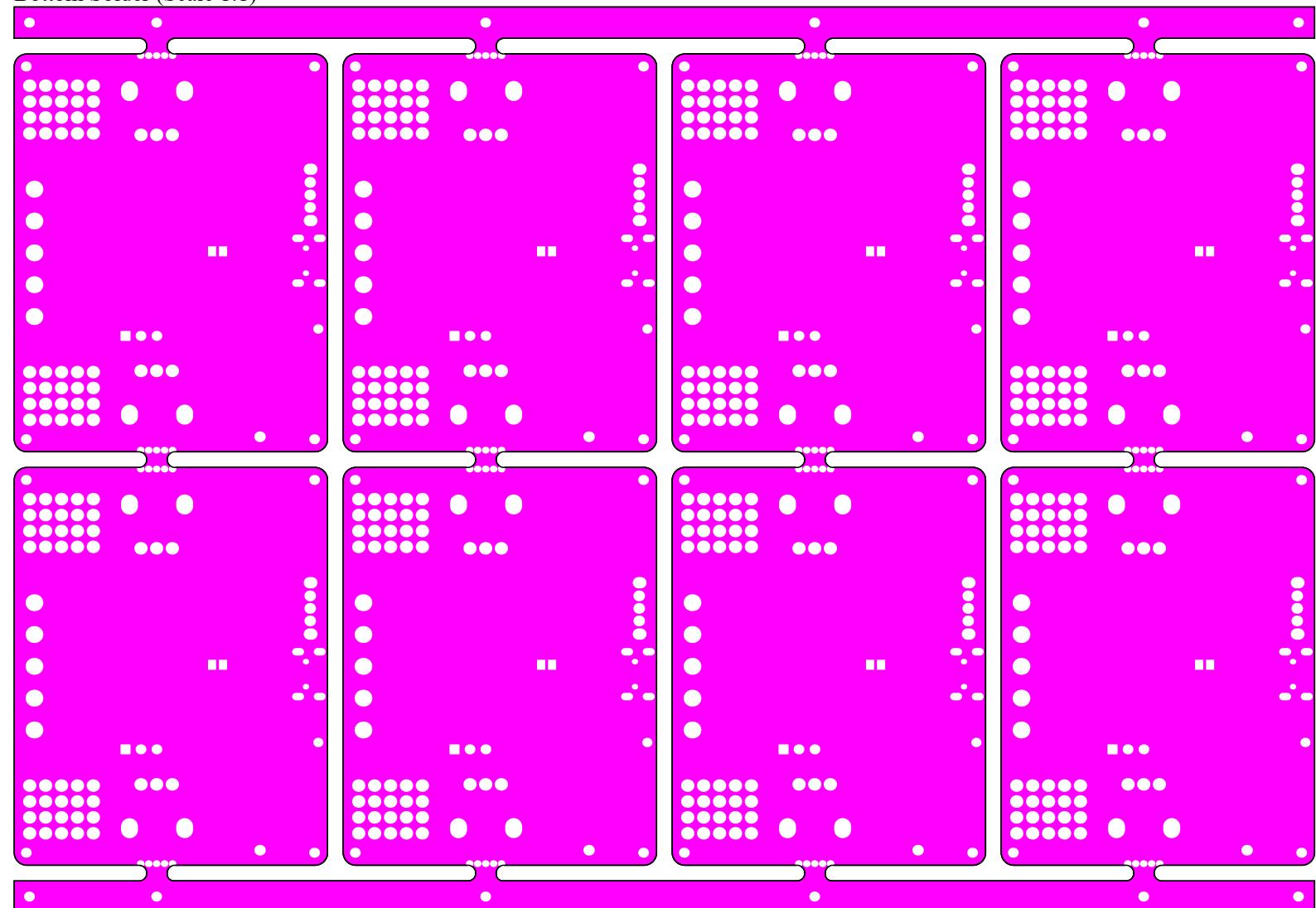
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Bottom Solder (Scale 1:1)



SIZE: A4 DWG: FABRICATION
SCALE: 1:1 FILE: Panel Fabrication.PCBDdwf SHEET 11 OF 11

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